

IN THE CLAIMS:

Please amend the claims on file and substitute the attached set of new claims with claims 1, 4, 8, 11, 14 and 18 shown as currently amended.

Kindly cancel claims 2-3 and 12-13, without prejudice.

CLAIMS



1. (Currently Amended) A light sensitive semiconductor package, comprising:

a chip carrier having an upper surface and an opposite lower surface,
wherein the chip carrier is formed with a through hole penetrating therethrough;

at least one first chip mounted on the upper surface of the chip carrier and
over the through hole with the first chip and electrically connected to the upper surface
of the chip carrier;

at least one second chip attached to the first chip and received in the
through hole of the chip carrier, such that the second chip is electrically connected to
the lower surface of the chip carrier;

a dam formed on the upper surface of the chip carrier and having a cavity
for receiving the first chip therein;

a first light permeable member attached to the dam to seal an opening of
the cavity and hermetically isolate the first chip from the atmosphere;

an encapsulant formed on the chip carrier ~~and surrounding~~ to surround the
dam and encapsulate the second chip; and

a second light permeable member supported by the encapsulant and
disposed above the first light permeable member.

2. (Cancelled)

3. (Cancelled)

4. (Currently Amended) The semiconductor package of claim 3 1, wherein the first
and second chips are electrically connected to the chip carrier by a plurality of
bonding wires, respectively.

5. (Original) The semiconductor package of claim 1, wherein the first light permeable member is an infrared filter.
6. (Original) The semiconductor package of claim 1, wherein the second light permeable member is a lens.
7. (Original) The semiconductor package of claim 1, wherein the chip carrier is a substrate or a lead frame.
8. (Currently Amended) The semiconductor package of claim 2 1, wherein the chip carrier is a substrate formed with the through hole, or a lead frame having a plurality of leads surrounding the through hole.
9. (Original) The semiconductor package of claim 1, wherein the dam is made of a material same as that for fabricating the encapsulant.
10. (Original) The semiconductor package of claim 1, wherein the dam is made of a material different from that for fabricating the encapsulant.
11. (Currently Amended) A fabrication method of a light sensitive semiconductor package, comprising the steps of:

preparing a chip carrier having an upper surface and an opposite lower surface, wherein the chip carrier is formed with a through hole penetrating therethrough;

mounting at least one first chip over the through hole and on the upper surface of the chip carrier and electrically connecting the first chip to the chip carrier;

attaching at least one second chip to the first chip and receiving the second chip in the through hole of the chip carrier, allowing the second chip to be electrically connected to the lower surface of the chip carrier;

forming a dam on the upper surface of the chip carrier, the dam having a cavity for receiving the first chip therein;

attaching a first light permeable member to the dam to seal an opening of the cavity and hermetically isolate the first chip from the atmosphere;

forming an encapsulant on the chip carrier to surround the dam and to encapsulate the second chip; and

mounting a second light permeable member to be supported by the encapsulant and disposed above the first light permeable member.

12. (Canceled)

13. (Canceled)

14. (Currently Amended) The fabrication method of claim ~~13~~ 11, wherein the first and second chips are electrically connected to the chip carrier by a plurality of bonding wires, respectively.

15. (Original) The fabrication method of claim 11, wherein the first light permeable member is an infrared filter.

16. (Original) The fabrication method of claim 11, wherein the second light permeable member is a lens.

17. (Original) The fabrication method of claim 11, wherein the chip carrier is a substrate or a lead frame.

18. (Currently Amended) The fabrication method of claim ~~12~~ 11, wherein the chip carrier is a substrate formed with the through hole, or a lead frame having a plurality of leads surrounding the through hole.

19. (Original) The fabrication method of claim 11, wherein the dam is made of a material same as that for fabricating the encapsulant.

20. (Original) The fabrication method of claim 11, wherein the dam is made of a material different from that for fabricating the encapsulant.